

INTERNATIONAL STANDARD

**Thermal standardization on semiconductor packages -
Part 6: Thermal resistance and capacitance model for transient temperature
prediction at junction and measurement points**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

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IEC 63378-6 has been prepared by subcommittee 47D: Semiconductor devices packaging, of IEC Technical Committee 47: Semiconductor devices. It is an International Standard.

The text of this International Standard is based on the following documents:

Draft	Report on voting
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Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.